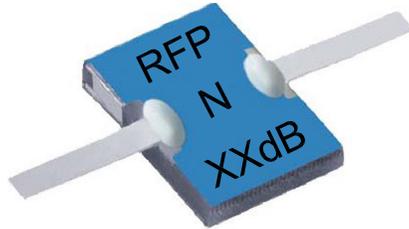




Flangeless Attenuator 100 Watts



General Specifications

Resistive Element	Thick film
Substrate	Aluminum Nitride ceramic
Lead(s):	99.99% pure silver (.005" thick)

Electrical Specifications

Attenuation Range:	1, 2, 3, 4, 5, 6, 10, 20 or 30 dB
Frequency Range;	DC – See Chart
Power:	100 Watts
VSWR	1.25:1

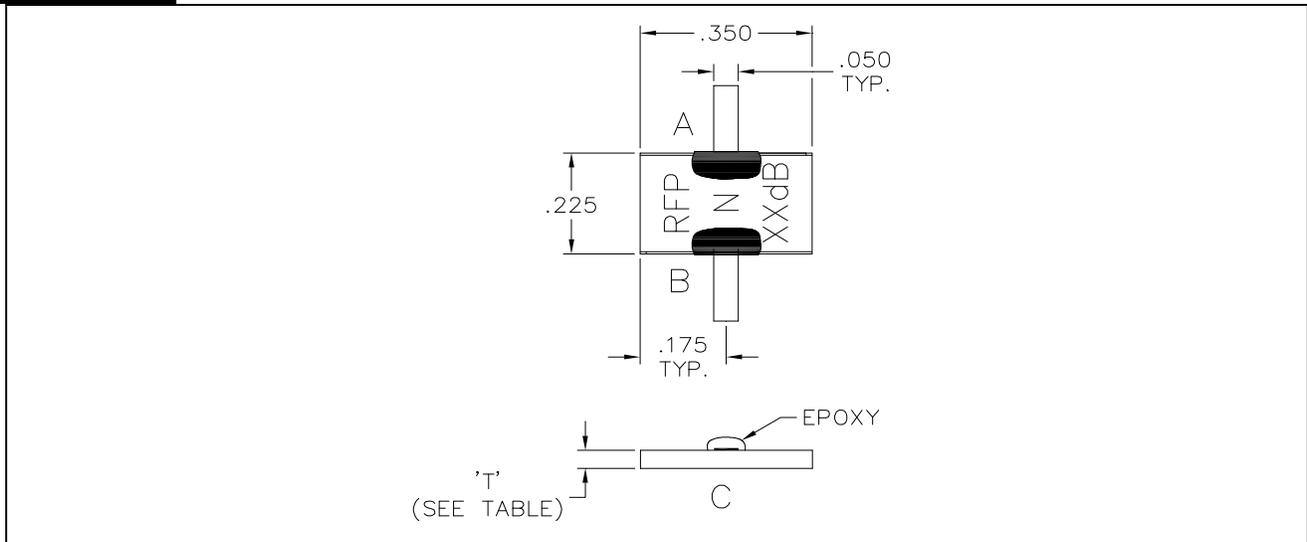
Note: Tolerance is ± 0.010 ", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. Operating temperature is -55°C to 150°C (see chart for derating temperatures). All dimensions in inches.

Specifications subject to change with out notice.

Features:

- DC – 3.0 GHz
- 100 Watts
- AlN Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

Outline Drawing



100NXXAF (097) Rev D

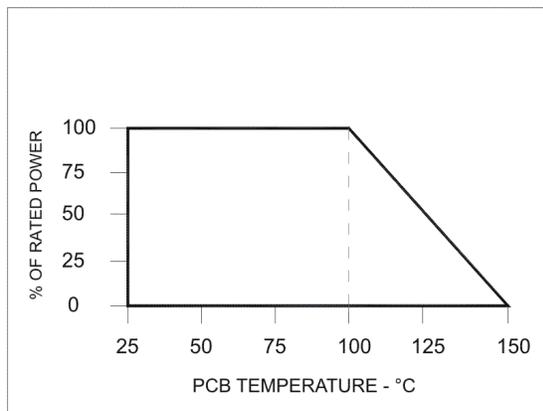




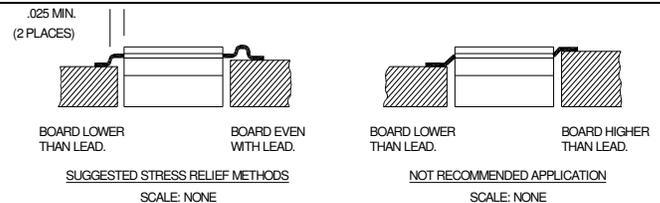
Typical Performance:

RESISTOR VALUE CHART							
ATTENUATION	VALUE (A-B)	VALUE (A-C)	VALUE (B-C)	TOL.	FREQUENCY	R.F.P. STOCK P/N	THICKNESS
1dB±0.25dB	4.8Ω	435 Ω	435 Ω	±4%	DC-2.2GHz.	RFP-100N1AF	.060
2dB±0.40dB	9.6Ω	232 Ω	232 Ω	±4%	DC-2.2GHz.	RFP-100N2AF	.060
3dB±0.40dB	15.2Ω	155 Ω	155 Ω	±4%	DC-2.5GHz.	RFP-100N3AF	.060
4dB±0.40dB	22Ω	151 Ω	151 Ω	±4%	DC-2.5GHz.	RFP-100N4AF	.060
5dB±0.40dB	28.5Ω	94.7Ω	94.7Ω	±4%	DC-3.0GHz.	RFP-100N5AF	.060
6dB±0.40dB	33.7Ω	82.5 Ω	82.5 Ω	±4%	DC-3.0GHz.	RFP-100N6AF	.060
9dB±0.75dB	50.6Ω	64.1Ω	63.3Ω	±4%	DC-2.2GHz.	RFP-100N9AF	.060
10dB±0.75dB	54.0Ω	59.8Ω	59.8Ω	±4%	DC-2.2GHz.	RFP-100N10AF	.060
20dB±0.50dB	248Ω	61.0 Ω	61.0 Ω	±4%	DC-2.0GHz.	RFP-100N20AF	.040
30dB±0.50dB	790Ω	53.0 Ω	53.0 Ω	±4%	DC-2.5GHz.	RFP-100N30AF	.040

Power De-rating:



Mounting Footprint and Procedure:



SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING APPROPRIATE SOLDER WITH A CONTROLLED TEMPERATURE IRON.

** FOR MORE DETAILS CONTACT FACTORY **

100NXXAF (097) Rev D

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Toll Free: (800) 544-2414
Europe: +44 2392-232392

Available on Tape and Reel For Pick and Place Manufacturing.



Anaren
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